

CLAIMS:

1. A wire bonding method in which primary bonding is performed on a first conductor, and then secondary bonding is performed on a second conductor, thus wire-bonding between said first conductor and second conductor, said method comprising the sequential steps of:

forming a bump by performing ball bonding by wire on said second conductor,
raising a capillary to a height that is equal to or lower than a height of a ball portion that rises into a through-hole of said capillary during formation of said bump,
moving said capillary in a direction opposite from said first conductor,
lowering said capillary so as to form an inclined wedge on said bump,
cutting said wire,
performing said primary bonding on said first conductor, and
making a loop with said wire with respect to said bump from said first conductor, thus performing said secondary bonding on said inclined wedge on said bump.